## General Description

The AUR9716 is a high efficiency step-down DC-DC voltage converter. The chip operation is optimized by peak-current mode architecture with built-in synchronous power MOS switchers. It is automatically switching between the normal PWM mode and LDO mode to offer improved system power efficiency covering a wide range of loading conditions.

Switching frequency during 1.0 MHz to 1.4 MHz is set by an external resistor and integrated soft-start (SS), under-voltage-lock-out (UVLO), thermal shutdown detection (TSD) and short circuit protection are designed to provide reliable product applications.

The device is available in adjustable output voltage versions ranging from 0.8 V to $\mathrm{V}_{\text {IN }}$ when input voltage range is from 2.5 V to 5.5 V , and is able to deliver up to 2 A .

The AUR9716 is available in DFN-3 $\times 3-8$ package.

## Features

- High efficiency Buck Power Converter
- Low Quiescent Current
- 2A Output Current
- Low $\mathrm{R}_{\mathrm{DS}(\mathrm{ON})}$ Internal Switches: $110 \mathrm{~m} \Omega$
- Adjustable Output Voltage from 0.8 V to $\mathrm{V}_{\text {IN }}$
- Wide Operating Voltage Range: 2.5 V to 5.5 V
- Built-in Power Switches for Synchronous Rectification with high Efficiency
- 800 mV Feedback Voltage Allows output
- Programmable Frequency: 1.0 MHz to 1.4 MHz
- Thermal Shutdown Protection
- Low Drop-out Operation at 100\% Duty Cycle
- No Schottky Diode Required


## Applications

- LCD TV
- Post DC-DC Voltage Regulation
- PDA and Notebook Computers


Figure 1. Package Type of AUR9716

## Pin Configuration

## D Package <br> (DFN-3×3-8)



Figure 2. Pin Configuration of AUR9716 (Top View)

## Pin Description

| Pin Number | Pin Name | Function |
| :---: | :---: | :--- |
| 1 | COMP | Compensation Point. COMP is used to compensate the regulation control <br> loop. Connect R and C from COMP and GND to compensate the regulation <br> control loop |
| 2 | GND | Ground. The exposed pad is soldered to PCB and connected to GND plant <br> for good power dissipation |
| 3 | EN | Enable Input. EN is an input when the regulator on or off. When left <br> unconnected, EN pin is pulled to VDD by the internal pull up resistor |
| 4 | VDD | Power input V IN provides the input power to the regulator. Connecting a <br> ceramic bypass capacitor between VDD and GND to eliminate input <br> noise and ripple voltage |
| 5 | SW | Switch Output. SW is the switching point which supplies voltage and <br> current to output |
| 6 | F_ADJ | Oscillator Resistor Input. Connecting a resistor to ground from this pin sets <br> the switching frequency |
| 7 | FB | Feedback Input. Receives the feedback voltage from a resistive divider <br> connected across the output. The feedback reference voltage is 0.8V <br> typically |
| 8 |  |  |

## Functional Block Diagram



Figure 3. Functional Block Diagram of AUR9716

## Ordering Information



| Package | Temperature <br> Range | Part Number | Marking ID | Packing Type |
| :---: | :---: | :--- | :--- | :--- |
| DFN $-3 \times 3-8$ | -40 to $80^{\circ} \mathrm{C}$ | AUR9716AGD | 9716 A | Tape \& Reel |

BCD Semiconductor's Pb -free products, as designated with " G " in the part number, are RoHS compliant and green.

Absolute Maximum Ratings (Note 1)

| Parameter | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| Supply Input Voltage | $\mathrm{V}_{\mathrm{IN}}$ | -0.3 to 6.0 | V |
| SW Pin Switch Voltage | $\mathrm{V}_{\mathrm{SW}}$ | -0.3 to $\mathrm{V}_{\text {IN }}+0.3$ | V |
| Output Voltage | $\mathrm{V}_{\mathrm{EN}}$ | -0.3 to $\mathrm{V}_{\text {IN }}+0.3$ | V |
| P-MOSFET Switch Source Current | $\mathrm{I}_{\text {SW-P }}$ | 3.5 | A |
| N-MOSFET Switch Sink Current | $\mathrm{I}_{\text {SW-N }}$ | 3.5 | A |
| Power Dissipation (on PCB, $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ ) | $\mathrm{P}_{\mathrm{D}}$ | 2.56 | W |
| Package Thermal Resistance (Junction to Ambient) | $\theta_{\mathrm{JA}}$ | 39.13 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Package Thermal Resistance (Junction to Case) | $\theta_{\mathrm{JC}}$ | 3.39 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Lead Temperature (Soldering, 5sec) | $\mathrm{T}_{\text {LEAD }}$ | 260 | ${ }^{\circ} \mathrm{C}$ |
| Junction Temperature | $\mathrm{T}_{\mathrm{J}}$ | 150 | ${ }^{\circ} \mathrm{C}$ |
| Operating Temperature Range | $\mathrm{T}_{\mathrm{OP}}$ | -40 to 85 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range | $\mathrm{T}_{\mathrm{STG}}$ | -55 to 150 | ${ }^{\circ} \mathrm{C}$ |
| ESD (Human Body Model) | $\mathrm{V}_{\mathrm{HBM}}$ | 2000 | $\mathrm{~V}^{\mathrm{V}}$ |
| ESD (Machine Model) | $\mathrm{V}_{\mathrm{MM}}$ | 200 | $\mathrm{~V}^{\mathrm{V}}$ |

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

## Recommended Operating Conditions

| Parameter | Symbol | Min | Max | Unit |
| :--- | :---: | :---: | :---: | :---: |
| Supply Input Voltage | $\mathrm{V}_{\text {IN }}$ | 2.5 | 5.5 | V |
| Junction Temperature Range | $\mathrm{T}_{\mathrm{J}}$ | -20 | 125 | ${ }^{\circ} \mathrm{C}$ |
| Operating Temperature Range | $\mathrm{T}_{\mathrm{A}}$ | -40 | 80 | ${ }^{\circ} \mathrm{C}$ |

## Electrical Characteristics

$\mathrm{V}_{\mathrm{IN}}=5 \mathrm{~V}, \mathrm{~V}_{\mathrm{FB}}=0.8 \mathrm{~V}, \mathrm{f}_{\mathrm{OSC}}=1.4 \mathrm{MHz}, \mathrm{L}=1.5 \mu \mathrm{H}, \mathrm{C}_{\mathrm{IN}}=10 \mu \mathrm{~F}, \mathrm{C}_{\mathrm{OUT}}=10 \mu \mathrm{~F}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise specified.

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Input Voltage Range | $\mathrm{V}_{\text {IN }}$ |  | 2.5 |  | 5.5 | V |
| Shutdown Current | $\mathrm{I}_{\text {OFF }}$ | $\mathrm{V}_{\mathrm{EN}}=0 \mathrm{~V}$ |  | 0.1 | 1 | $\mu \mathrm{A}$ |
| Active Current | $\mathrm{I}_{\mathrm{ON}}$ | $\mathrm{V}_{\mathrm{FB}}=0.95 \mathrm{~V}$ |  | 460 |  | $\mu \mathrm{A}$ |
| Regulated Feedback Voltage | $\mathrm{V}_{\mathrm{FB}}$ | For adjustable output voltage | 0.784 | 0.8 | 0.816 | V |
| Regulated Output Voltage | $\Delta V_{\text {OUT }}$ $/ V_{\text {OUT }}$ | $\begin{aligned} & \mathrm{V}_{\mathrm{IN}}=2.5 \mathrm{~V} \text { to } 5.5 \mathrm{~V}, \\ & \mathrm{I}_{\mathrm{OUT}}=0 \mathrm{~A} \text { to } 2 \mathrm{~A} \end{aligned}$ | -3 |  | 3 | \% |
| Peak Inductor Current | $\mathrm{I}_{\text {PK }}$ | $\mathrm{V}_{\mathrm{FB}}=0.7 \mathrm{~V}$ | 2.2 | 3.2 | 3.7 | A |
| Oscillator Frequency | $\mathrm{f}_{\text {OSC }}$ | $\mathrm{R}_{\mathrm{OSC}}=5.1 \mathrm{M} \Omega$ | 1.12 | 1.4 | 1.68 | MHz |
|  |  | Adjustable switching frequency | 1.0 |  | 1.4 |  |
| $\mathrm{P}_{-}$MOSFET R $\mathrm{O}_{\text {ON }}$ | $\mathrm{R}_{\text {DSON(P) }}$ | $\mathrm{I}_{\text {SW }}=0.5 \mathrm{~A}$ | 90 | 110 | 130 | $\mathrm{m} \Omega$ |
| N_MOSFET $\mathrm{R}_{\text {ON }}$ | $\mathrm{R}_{\text {DSON(N) }}$ | $\mathrm{I}_{\mathrm{SW}}=0.5 \mathrm{~A}$ | 90 | 110 | 130 | $\mathrm{m} \Omega$ |
| EN Input High-Threshold Voltage | $\mathrm{V}_{\text {ENH }}$ | Enable Threshold | 1.5 |  |  | V |
| EN Input Low-Threshold Voltage | $\mathrm{V}_{\text {ENL }}$ | Shutdown Threshold |  |  | 0.4 | V |
| EN Input Current | $\mathrm{I}_{\mathrm{EN}}$ |  |  | 2 |  | $\mu \mathrm{A}$ |
| Soft-start Time | $\mathrm{t}_{\text {SS }}$ |  |  | 800 |  | $\mu \mathrm{s}$ |
| Maximum Duty Cycle | $\mathrm{D}_{\text {MAX }}$ |  | 100 |  |  | \% |
| Under Voltage Lock Out Threshold | $\mathrm{V}_{\text {UVLO }}$ | $\mathrm{V}_{\text {IN }}$ Rising |  | 2.4 |  | V |
|  |  | $\mathrm{V}_{\text {IN }}$ Falling |  | 2.3 |  |  |
|  |  | Hysteresis |  | 0.1 |  |  |
| Thermal Shutdown | $\mathrm{T}_{\mathrm{SD}}$ | Hysteresis $=30^{\circ} \mathrm{C}$ |  | 150 |  | ${ }^{\circ} \mathrm{C}$ |
| Error Amplifier Trans Conductance | $\mathrm{g}_{\mathrm{m}}$ |  |  | 3000 |  | $\mu \mathrm{s}$ |
| Current Sense Trans Resistance 有 | $\mathrm{R}_{\mathrm{T}}$ |  |  | 5 |  | $\Omega$ |

## Typical Performance Characteristics



Figure 4. Output Current vs.Efficiency


Figure 6. Output Current vs.Efficiency


Figure 8. Output Current vs.Efficiency


Figure 5. Output Voltage vs. Output Current


Figure 7. Output Voltage vs. Output Current


Figure 9. Output Voltage vs. Output Current

## Typical Performance Characteristics (Continued)



Figure 10. Input Voltage vs. Shutdown Current


Figure 12. Input Voltage vs. P_MOSFET RDS


Figure 14. Load Regulation $\left(\mathrm{V}_{1 \mathrm{~N}}=5 \mathrm{~V}, \mathrm{~V}_{\mathrm{OUT}}=1.1 \mathrm{~V}\right.$, $\mathrm{f}_{\mathrm{OSc}}=1.4 \mathrm{MHz}, \mathrm{l}_{\text {out }}=0.1 \mathrm{~A}$ to 2 A )


Figure 11. Input Voltage vs. Quiescent Current


Figure 13. Input Voltage vs. N_MOSFET RDS


Figure 15. Load Regulation ( $\mathrm{V}_{\text {IN }}=5 \mathrm{~V}$, $\mathrm{V}_{\text {OUT }}=1.1 \mathrm{~V}$, $\mathrm{f}_{\mathrm{OSc}}=1.2 \mathrm{MHz}, \mathrm{l}_{\text {out }}=0.1 \mathrm{~A}$ to 2 A )

## Typical Performance Characteristics (Continued)



Figure 16. Load Regulation ( $\mathrm{V}_{\text {IN }}=5 \mathrm{~V}, \mathrm{~V}_{\mathrm{OUT}}=1.1 \mathrm{~V}$, $\mathrm{f}_{\mathrm{Osc}}=1.0 \mathrm{MHz}$, lout $=0.1 \mathrm{~A}$ to 2 A )


Figure 18. Power Start-up $\left(\mathrm{V}_{\mathbb{N}}=0 \mathrm{~V}\right.$ to 5 V ,
$V_{\text {OUT }}=3.3 \mathrm{~V}$, fosc $=1.2 \mathrm{MHz}$, lout $=2 \mathrm{~A}$ )


Figure 20. Power Turn-off $\left(\mathrm{V}_{\mathrm{IN}}=5 \mathrm{~V}\right.$ to 0 V , $\mathrm{V}_{\text {OUT }}=3.3 \mathrm{~V}$, fosc $=1.4 \mathrm{MHz}$, lout $=2 \mathrm{~A}$ )


Figure 17. Power Start-up $\left(\mathrm{V}_{\mathbb{1}}=0 \mathrm{~V}\right.$ to 5 V , $\mathrm{V}_{\text {OUT }}=3.3 \mathrm{~V}, \mathrm{f}_{\text {OSC }}=1.4 \mathrm{MHz}$, $\mathrm{l}_{\text {OUT }}=2 \mathrm{~A}$ )


Figure 19. Power Start-up $\left(\mathrm{V}_{\mathbb{1}}=0 \mathrm{~V}\right.$ to 5 V , $\mathrm{V}_{\text {OUT }}=3.3 \mathrm{~V}, \mathrm{f}_{\text {OSC }}=1.0 \mathrm{MHz}, \mathrm{l}_{\text {OUT }}=2 \mathrm{~A}$ )


Figure 21. Power Turn-off $\left(\mathrm{V}_{\mathbb{I N}}=5 \mathrm{~V}\right.$ to 0 V , $\mathrm{V}_{\text {OUT }}=3.3 \mathrm{~V}$, fosc $=1.2 \mathrm{MHz}$, lout $=2 \mathrm{~A}$ )

## Typical Performance Characteristics (Continued)



Figure 22. Power Turn-off $\left(\mathrm{V}_{\mathbb{I}}=5 \mathrm{~V}\right.$ to 0 V , $\mathrm{V}_{\text {out }}=3.3 \mathrm{~V}, \mathrm{fosc}=1.0 \mathrm{MHz}$, lout $=2 \mathrm{~A}$ )

## AUR9716

## Application Information

The AUR9716 is a synchronous buck converter which can support switching frequency range from 1.0 MHz to 1.4 MHz and the output current can be up to 2 A .

The basic AUR9716 application circuits are shown as Figure 27, external components selection is determined by the load current and is critical with the selection of inductor and capacitor values.

## 1. Inductor Selection

For most applications, the value of inductor is chosen based on the required ripple current with the range of $1.5 \mu \mathrm{H}$ to $4.7 \mu \mathrm{H}$.
$\Delta I_{L}=\frac{1}{f \times L} V_{\text {OUT }}\left(1-\frac{V_{\text {OUT }}}{V_{I N}}\right)$
The largest ripple current occurs at the highest input voltage. Having a small ripple current reduces the ESR loss in the output capacitor and improves the efficiency. The highest efficiency is realized at low operating frequency with small ripple current. However, the larger value inductors will be required. A reasonable starting point for ripple current setting is $\Delta \mathrm{I}_{\mathrm{L}}=40 \% \mathrm{I}_{\mathrm{MAX}}$. For a maximum ripple current stays below a specified value, the inductor should be chosen according to the following equation:

$$
L=\left[\frac{V_{\text {OUT }}}{f \times \Delta I_{L}(M A X)}\right]\left[1-\frac{V_{\text {OUT }}}{V_{I N}(M A X)}\right]
$$

The DC current rating of the inductor should be at least equal to the maximum output current plus half of the highest ripple current to prevent inductor core saturation. For better efficiency, the lower DC-resistance inductor should be selected.

## 2. Capacitor Selection

The input capacitance, $\mathrm{C}_{\mathrm{IN}}$, is needed to filer the trapezoidal current at the source of the top MOSFET. To prevent the large ripple voltage, a low ESR input capacitor sized for the maximum RMS current must be used. The maximum RMS capacitor current is given by:
$I_{\text {RMS }}=I_{\text {OMAX }} \times \frac{\left[V_{\text {OUT }}\left(V_{I N}-V_{\text {OUT }}\right)\right]^{\frac{1}{2}}}{V_{I N}}$
It indicates a maximum value at $\mathrm{V}_{\text {IN }}=2 \mathrm{~V}_{\text {OUT }}$, where $\mathrm{I}_{\text {RMS }}=\frac{\mathrm{I}_{\mathrm{OUT}}}{2}$. This simple worse-case condi-
tion is commonly used for design because even significant deviations do not much relief. The selection of $\mathrm{C}_{\text {Out }}$ is determined by the equivalent series resistance (ESR) that is required to minimize output voltage ripple and load step transients, as well as the amount of bulk capacitor that is necessary to ensure the control loop is stable. Loop stability can be also checked by viewing the load step transient response as described in a latter section. The output ripple, $\Delta \mathrm{V}_{\mathrm{OUT}}$, is determined by:
$\Delta V_{\text {OUT }} \leq \Delta I_{L}\left[E S R+\frac{1}{8 \times f \times C_{\text {OUT }}}\right]$
The output ripple is the highest at the maximum input voltage since $\Delta \mathrm{I}_{\mathrm{L}}$ increases with input voltage.

## 3. Load Transient

A switching regulator typically takes several cycles to respond to the load current step. When a load step occurs, $\mathrm{V}_{\text {OUT }}$ immediately shifts by an amount equal to ( $\Delta \mathrm{I}_{\text {LOAD }} \times \mathrm{ESR}$ ), where ESR is the equivalent series resistance of output capacitor. $\Delta I_{\text {LOAD }}$ also begins to charge or discharge $\mathrm{C}_{\text {OUT }}$ generating a feedback error signal used by the regulator to return $\mathrm{V}_{\text {Out }}$ to its steady-state value. During the recovery time, $\mathrm{V}_{\text {OUT }}$ can be monitored for overshoot or ringing that would indicate a stability problem.

## 4. Output Voltage Setting

The output voltage of AUR9716 can be adjusted by a resistive divider according to the following formula:
$V_{O U T}=V_{F B} \times\left(1+\frac{R_{1}}{R_{2}}\right)=0.8 V \times\left(1+\frac{R_{1}}{R_{2}}\right)$
When $\mathrm{V}_{\mathrm{FB}}$ is the 0.8 V feedback reference voltage, the resistive divider senses the fraction of the output voltage as shown in Figure 23.


Figure 23. Setting the Output Voltage

## Application Information (Continued)

## 5. Slope Compensation

The slope compensation of AUR9716 provides stability in constant frequency construction by preventing oscillations at duty cycle more than $50 \%$. It's accomplished externally by adding a series of capacitor and resistor, as shown in Figure 24.


Figure 24. Stability Compensation Components
The DC loop gain of the system is determined by the following equation:

$$
A_{V D C}=\frac{V_{F B}}{I_{O U T}} A_{V} G_{C S},
$$

Where $A_{V}$ is error amplifier voltage gain and $G_{C S}$ is current sense transconductance.

The dominant pole P 1 is due to $\mathrm{C}_{\text {COMP }}$ :
$f_{P 1}=\frac{G_{E A}}{2 \pi A_{V} C_{\text {COMP }}}$,
Where $G_{E A}$ is error amplifier transconductance.
The output pole P 2 is due to $\mathrm{C}_{\text {out }}$ :
$\mathrm{f}_{\mathrm{P}_{2}}=\frac{\mathrm{I}_{\text {OUT }}}{2 \pi \mathrm{~V}_{\text {OUT }} \mathrm{C}_{\text {OUT }}}$
The zero Z 1 is due to $\mathrm{C}_{\text {COMP }}$ and $\mathrm{R}_{\text {COMP }}$ :
$f_{Z 1}=\frac{1}{2 \pi R_{\text {COMP }} C_{\text {COMP }}}$
If $\mathrm{C}_{\text {COMP2 }}$ is used, the third pole is due to $\mathrm{R}_{\text {COMP }}$ and Comp2: $^{\text {C }}$

Then the cross over frequency often sets at $1 / 5$ to $1 / 10$ of the switching frequency.

Table 1 shows some calculated results based on stability compensation equations above.

| Switching Frequency <br> $(\mathrm{MHz})$ | 1.4 | 1.2 | 1.0 |
| :---: | :---: | :---: | :---: |
| $\mathrm{R}_{\mathrm{COMP}}(\mathrm{k} \Omega)$ | 4.3 | 4.3 | 3.6 |
| $\mathrm{C}_{\mathrm{COMP}}(\mathrm{nF})$ | 1 | 1 | 1.5 |
| $\mathrm{~L}(\mu \mathrm{H})$ | 1.5 | 1.5 | 2.2 |
| $\mathrm{C}_{\text {OUT }}(\mu \mathrm{F})$ | 10 | 10 | 10 |

Table 1. Stability Compensation Components
To optimize the components for stability compensation listed in Table 1, we will introduce the selection value of $\mathrm{R}_{\mathrm{COMP}}$ and $\mathrm{C}_{\text {COMP }}$ as detail as possible.

1. $\mathrm{R}_{\text {COMP }}$ : determine this resistor value according to the desired crossover frequency is $f_{C}$, default as 1.4 MHz .
$R_{\text {COMP }}=\frac{2 \pi C_{\text {OUT }} f_{C}}{G_{E A} G_{C S}} \frac{V_{\text {OUT }}}{V_{F B}}$
2. $\mathrm{C}_{\text {СомP }}$ : determine this capacitor value according to the desired phase margin. We often choose this compensation.

Zero point below one forth of the crossover frequency to ensure the loop stability.

$$
C_{\text {COMP }}>\frac{4}{2 \pi R_{\text {COMP }} f_{C}}
$$

## 6. Short-Circuit Protection

When AUR9716 output node is shorted to GND, as $\mathrm{V}_{\mathrm{FB}}$ drops under 0.4 V , chip will enter soft-start to protect itself, when short circuit is removed, and $\mathrm{V}_{\mathrm{FB}}$ rises over 0.4 V , the AUR9716 enters normal operation again. If AUR9716 reaches OCP threshold while short circuit, it will enter soft-start cycle until the current under OCP threshold. When AUR9716 is used to transfer $\mathrm{V}_{\text {IN }}=5 \mathrm{~V}$ to $\mathrm{V}_{\text {OUT }}=2.5 \mathrm{~V}$, shorting $\mathrm{V}_{\text {OUT }}$ to GND makes big current which enables SCP protection. The waveform is shown in Figure 25.

## Application Information (Continued)



Figure 25. SCP Protection

## 7. F_ADJ : Rosc Selection

The AUR9716 can change switching frequency by choose different $\mathrm{R}_{\mathrm{OSC}}$, please refer to Table 2.

| Switching Frequency <br> $(\mathrm{MHz})$ | 1.4 | 1.2 | 1.0 |
| :---: | :---: | :---: | :---: |
| $\mathrm{R}_{\mathrm{OSC}}(\mathrm{k} \Omega)$ | 5100 | 976 | 536 |

Table 2. Rosc Setting
Due to get the better performance of AUR9716, F_ADJ pin (Pin 7) could parallel 47pF capacitor with $\mathrm{R}_{\mathrm{OSC}}$, shown in Figure 26.


Figure 26. F_ADJ Components

## 8. Thermal Characteristics

The max power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of temperature between junction to ambient. The max power dissipation can be calculated by following formula:
$P_{D(M A X)}=\left(\frac{T_{J(M A X)}-T_{A}}{\theta_{J A}}\right)$
Where $\mathrm{T}_{\mathrm{J}(\max )}$ is the maximum operation junction temperature, $\mathrm{T}_{\mathrm{A}}$ is the ambient temperature and $\theta_{\mathrm{JA}}$ is the junction to ambient thermal resistance.

## 9. PC Board Layout Considerations

When laying out the printed circuit board, the following checklist should be used to optimize the performance of AUR9716.

1. The power traces, including the GND trace, the SW trace and the VDD trace should be kept direct, short and wide.
2. To put the input capacitor as close as possible to the VDD and GND pins.
3. The FB pin should be connected directly to the feedback resistor divider.
4. Keep the switching node, SW, away from the sensitive FB pin and the node should be kept small area.

## Typical Application



Figure 27. Typical Application Circuit of AUR9716 (Switching Frequency=1.0MHz to 1.4 MHz )

| $\mathrm{V}_{\text {OUT }}(\mathrm{V})$ | $\mathrm{R} 1(\mathrm{k} \Omega)$ | $\mathrm{R} 2(\mathrm{k} \Omega)$ |
| :---: | :---: | :---: |
| 3.3 | 6.25 | 2 |
| 2.5 | 4.25 | 2 |
| 1.8 | 2.5 | 2 |
| 1.1 | 0.75 | 2 |


| Switching Frequency <br> $(\mathrm{MHz})$ | $\mathrm{R}_{\text {OSC }}$ <br> $(\mathrm{k} \Omega)$ | $\mathrm{R}_{\text {COMP }}$ <br> $(\mathrm{k} \Omega)$ | $\mathrm{C}_{\text {COMP }}$ <br> $(\mathrm{nF})$ | L <br> $(\mu \mathrm{H})$ | $\mathrm{C}_{\text {OUT }}$ <br> $(\mu \mathrm{F})$ |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 1.0 | 536 | 3.6 | 1.5 | 2.2 | 10 |
| 1.2 | 976 | 4.3 | 1.0 | 1.5 | 10 |
| 1.4 | 5100 | 4.3 | 1.0 | 1.5 | 10 |

## Mechanical Dimensions

DFN-3×3-8
Unit:mm(inch)


## BCH A

# BCD Semiconductor Manufacturing Limited 

## http://www.bcdsemi.com

## IMPORTANT NOTICE

BCD Semiconductor Manufacturing Limited reserves the right to make changes without further notice to any products or specifications herein. BCD Semiconductor Manufacturing Limited does not assume any responsibility for use of any its products for any particular purpose, nor does BCD Semiconductor Manufacturing Limited assume any liability arising out of the application or use of any its products or circuits. BCD Semiconductor Manufacturing Limited does not convey any license under its patent rights or other rights nor the rights of others.

## MAIN SITE

## - Headquarters

BCD Semiconductor Manufacturing Limited
No. 1600, Zi Xing Road, Shanghai ZiZhu Science-based Industrial Park, 200241, China
Tel: +86-21-24162266, Fax: +86-21-24162277

## REGIONAL SALES OFFICE

## Shenzhen Office

Shanghai SIM-BCD Semiconductor Manufacturing Co., Ltd., Shenzhen Office
Unit A Room 1203, Skyworth Bldg., Gaoxin Ave.1.S., Nanshan District, Shenzhen,
China
Tel: +86-755-8826 7951
Fax: +86-755-8826 7865

## - Wafer Fab

Shanghai SIM-BCD Semiconductor Manufacturing Co., Ltd.
800 Yi Shan Road, Shanghai 200233, China
Tel: +86-21-6485 1491, Fax: +86-21-5450 0008

## Taiwan Office

BCD Semiconductor (Taiwan) Company Limited 4F, 298-1, Rui Guang Road, Nei-Hu District, Taipei, Taiwan
Tel: +886-2-2656 2808
Fax: +886-2-2656 2806

USA Office
BCD Semiconductor Corp. 30920 Huntwood Ave. Hayward, CA 94544, USA Tel : +1-510-324-2988
Fax: +1-510-324-2788

